

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

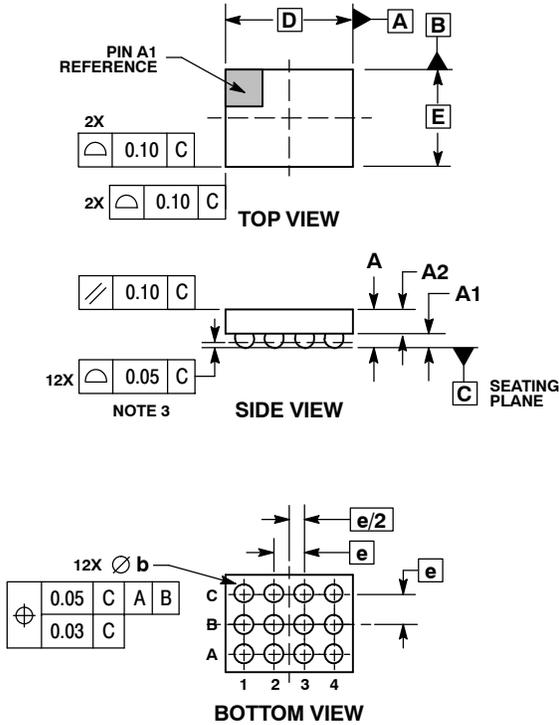
ON Semiconductor®



12 PIN FLIP-CHIP, 2.0x1.5, 0.5P  
CASE 499AZ-01  
ISSUE O

DATE 20 MAY 2008

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.54	0.60
A1	0.21	0.27
A2	0.33	0.39
b	0.29	0.34
D	2.00 BSC	
E	1.50 BSC	
e	0.50 BSC	

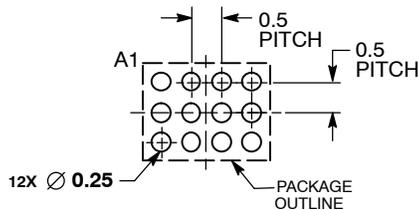
**GENERIC MARKING DIAGRAM\***



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**SOLDERING FOOTPRINT\***



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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	12 PIN FLIP-CHIP, 2.0 X 1.5, 0.5P	<b>PAGE 1 OF 2</b>

